

Title (en)  
Laser welding device and method

Title (de)  
Verfahren und Vorrichtung zum Laserschweißen

Title (fr)  
Procédé et dispositif de soudage au laser

Publication  
**EP 0691174 A1 19960110 (EN)**

Application  
**EP 95304727 A 19950706**

Priority  
JP 18071194 A 19940708

Abstract (en)  
In a laser welding device, a photographing device (31) is provided to photograph the plasma (7) caused by exposing an object to laser beams (6). An image processing device (33) is provided to measure at least one of an area and height of a plasma image photographed by the photographing device (31). A distinction device (34) is provided to compare a value measured by the image processing device (33) with an allowable value so as to determine whether the laser welding condition is good or not. <MATH>

IPC 1-7  
**B23K 26/02**

IPC 8 full level  
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CPC (source: EP US)  
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Citation (search report)

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